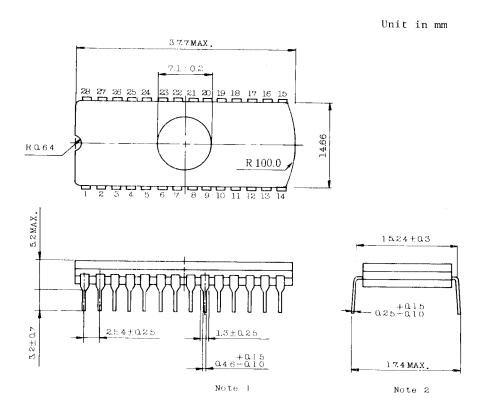
# TMM27128AD-15, TMM27128AD-150 TMM27128AD 20, TMM27128AD-200

## **OUTLINE DRAWINGS**



Note: 1. Each lead pitch is 2.54mm. All leads are located within 0.25mm of their true longitudinal position with respect No.1 and No.28 leads.

- 2. This value is measured at the end of leads.
- 3. All dimensions are in millimeters.

# **TOSHIBA MOS MEMORY PRODUCTS**

32,768 WORD  $\times$  8 BIT N-MOS UV ERASABLE AND ELECTRICALLY PROGRAMMABLE READ ONLY MEMORY SILICON STACKED GATE MOS

TMM27256AD-15, TMM27256AD-150 TMM27256AD-20, TMM27256AD-200

### DESCRIPTION

The TMM27256AD is a 32,768 word  $\times$  8 bit ultraviolet light erasable and electrically programmable read only memory.

For read operation, the TMM27256AD's access time is 150ns/200ns, and the TMM27256AD operates from a single 5-volt power supply and has low power standby mode which reduces the power dissipation without increasing access time. The standby

mode is achieved by applying a TTL-high level signal to the  $\overline{\text{CE}}$  input.

For program operation, the programming is achieved by using the high speed programming mode.

The TMM27256AD is fabricated with the N-channel silicon double layer gate MOS technology.

### **FEATURES**

	- 15	-20	150	-200	
Vcc	5V±	5V±5% 5			
tacc	150ns	200ns	150ns	200ns	
Icc2	100	)mA	120mA		
lcc1	301	mA	35r	ηA	

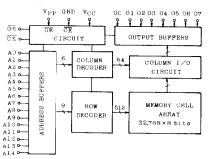
VPP[		28 þ	VCC
A12 d	2		A 1.4
A7 C	3		A13
A6 [	4	25	8A
A5 [	5		A9
A4 [	6	23 7	Al 1
АЗ [	7	22 )	OE
A2 [	8	21 0	A10
A1 4	9	20	CE
AO C	10	19 þ	07
00 <b>t</b>	11	18	06
01 🕻	12	17	05
05 🕻	13	16	04
GNDC	14	15 <b>þ</b>	03

PIN CONNECTION (TOP VIEW)

# • Full static operation

- High speed programming mode
- Inputs and outputs TTL compatible
- Pin compatible with i 27256
- Standard 28 pin DIP cerdip package

### **BLOCK DIAGRAM**



#### **PIN NAMES**

$A_0 \sim A_{14}$	Address Inputs
00~0/	Outputs (Inputs)
CE	Chip Enable Input
ŌE	Output Enable Input
Vpp	Program Supply Voltage
Vcc	Power Supply Voltage (+5V)
GND	Ground

### MODE SELECTION

PIN	CE	ŌĒ	VPP	Vcc	O <sub>0</sub> ~ O <sub>7</sub>	POWER
MODE	(20)	(22)	(1)	(28)	$(11\sim13, 15\sim19)$	TOVVEIL
Read	L	l_		(28) (11~13, 15~19  Data Out  5V High Impedance  High Impedance		
Output				<i>.</i>		Active
Deselect	*	H	5V	5V	High Impedance	
Standby	Н	*	]		High Impedance	Standby
Program	L	H			High Impedance Data In	
Program Inhibit	Н	Н	12.5V	6V	High Impedance	Active
Program Verify	*	L.			Data Out	

Note \* : H or L

### **MAXIMUM RATINGS**

SYMBOL	ITEM	RATING	7 UNIT
Vac	Power Supply Voltage	0.6~7.0	- V
Vəp	Program Supply Voltage	0.6~14.0	
Vin	Input Voltage	-0.6-7.0	
VI-0	Input/Output Voltage	0.6~7.0	
P <sub>0</sub>	Power Dissipation	1.5	
TSOLDER	Soldering Temperature · Time	260 · 10	°C·sec
Tsrg	Storage Temperature	-65~125	
Торя	Operating Temperature	0~70	

# **READ OPERATION**

# D. C. AND A.C. RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	TMM27256AD-15/20	TMM27256AD-150/200
Та	Operating Temperature	0~70°C	0~70°C
Vcc	Vcc Power Supply Voltage	5V±5%	5V±10%
VPP	VPP Power Supply Voltage	2.0 ~ V <sub>CC</sub> + 0.6V	2.0~Vcc · 0.6V

# D. C. AND OPERATING CHARACTERISTICS

SYMBOL	PARAMETER	СО	NDITION		MIN.	TYP.	MAX.	UNIT
l <sub>11</sub>	Input Current	VIN - 0 ~ VCC			T		+10	μA
lio_	Output Leakage Current	V <sub>001</sub> = 0.4 ~ V <sub>CC</sub>			·		± 10	μΑ
l Jeer	Supply Current (Standby)	CF = VIH		-15/20			30	
1	Cappy Carrett (Standby)	CE - VIH		150/200		† I	35	⊣ mA
l kee	Supply Current (Active)	CF VII	CE-V	5/20			100	
"	- Capply Carrent (Active)	CE VII		-150/200		†	120	mA
ViH	Input High Voltage				2.0		Vcc + 1.0	Ivi
l VII	Input Low Voltage				0.3		0.8	V
VoH	Output High Voltage	Ior400µA			2.4			V
Vol	Output Low Voltage	loi 2.1mA					0.4	V
12921	VPP Current	VPP = 0 ~ Vcc + 0.6					+1()	$\mu A$

### A.C. CHARACTERISTICS

 $(Ta=0\sim70^{\circ}C, V_{CC}=5V+5\%, V_{PP}=2.0V\sim V_{CC}+0.6V)$ 

SYMBOL	PARAMETER	TECT CONDITION	1MM2725€AD 15/150 IMM27256AD 207200				1
JIMBOL		TEST CONDITION	MIN.	MAX.	MIN.	MAX.	UNIT
tacc	Address Access Time	CE = OE = V <sub>IL</sub>	T -	150		200	ns
ta	CE to Output Valid	OE VII	T	150		200	ns
tor	OE to Output Valid	CE VII.		70		70	ns
tor i	CE to Output in High-Z	OE == VII	0	60	0	60	ns
tor 2	OE to Output in High-Z	CE - VII.	0	60	0	60	ns — -
ton	Output Data Hold Time	CE == OE == V <sub>IL</sub>	0		0	† · · · · · · · · · · · · · · · · · · ·	ns

### A. C. TEST CONDITIONS

Output Load

: 1 ITL Gate and C<sub>L</sub>=100pF

• Input Pulse Rise and Fall Times

: 10ns Max.

Input Pulse Levels

: 0.45V to 2.4V

Timing Measurement Reference Level

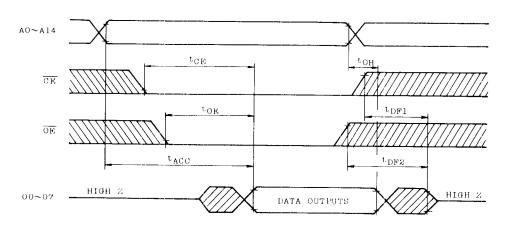
: Inputs 0.8V and 2.0V, Outputs 0.8V and 2.0V

### **CAPACITANCE** \* (Ta = 25°C, f = 1 MHz)

	SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
į	Cin	Input Capacitance	V <sub>IN</sub> = OV		4	6	pF
Ì	Соит	Output Capacitance	Vout=OV		8	12	pF

<sup>\*</sup> This paramater is periodically sampled and is not 100% tested.

### **TIMING WAVEFORMS (READ)**



## **PROGRAM OPERATION**

# D.C. RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VIH	Input High Voltage	2.0	_	Vcc + 1.0	V
Vil	Input Low Voltage	-0.3		0.8	V
Vcc	Vcc Power Supply Voltage	5.75	6.0	6.25	V
VPP	Ver Power Supply Voltage	12.0	12.5	13.0	V

# **D.C.** and OPERATING CHARACTERISTICS ( $Ta-25\pm5^{\circ}C$ , $V_{CC}-6V\pm0.25V$ , $V_{PP}-12.5V+0.5V$ )

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
10	Input Current	VIN=O~VCC			+10	μА
Voн	Output High Voltage	$I_{\text{OH}} = -400 \mu A$	2.4			V
Vot	Output Low Voltage	lot = 2 . 1 mA			0.4	V
Icc	Vcc Supply Current				120	mA
IPP2	VPP Supply Current	Vpp 13 . OV			50	mA

A. C. PROGRAMMING CHARACTERISTICS (Ta=25±5°C, Vcc=6V±0.25V, Vpp=12.5V±0.5V)

SYMBOL.	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNI
tas	Address Setup Time		1 2		+	μS
tан	Address Hold Time				ł	μS
ters	CE Setup Time				++	ns
torn	CE Hold Time		— <u> </u>			ns
toes	OE Setup Time				+	<u></u> μs
tos	Data Setup Time				++	<u>μ</u> S
ton	Data Hold Time				+ -+	μS
tves	V <sub>PP</sub> Setup Time				-	μS
tvcs	Vcc Setup Time		2		<u> </u>	μS
tew	Initial Program Pulse Width	CE = VIL, OE == VIH	0.95	1	1.05	ms
topw	Overprogram Pulse Width	Note 1	2.85	3	78.75	- ms
tot	OE to Output Valid	CE-VIH			150	ns
tore i	OE to Output in High-Z	CE = V <sub>IH</sub>			130	ns

### A. C. TEST CONDITIONS

• Output Load : 1 TTL Gate and C<sub>i</sub> (100pF)

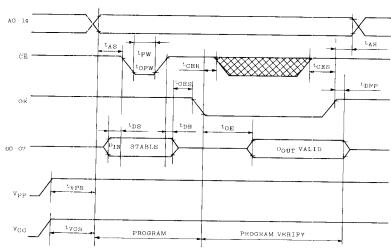
Input Pulse Rise and Fall Times : 10ns Max.
Input Pulse Levels : 0.45V to 2.4V

• Timing Measurement Reference Level : Input 0.8V and 2.0V, Output 0.8V and 2.0V

Note: 1. The length of the overprogram pulse may vary as a function of the counter value X.

### TIMING WAVEFORMS (PROGRAM)

 $(v_{CC} - 6v \pm 0.25v, v_{PP} = 12.5v \pm 0.5v)$ 



Note: 1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$  and cut off simultaneously or after  $V_{PP}$ .

- 2. Removing the device from socket and setting the device in socket with  $V_{PP} = 12.5V$  may cause permanent damage to the device.
- 3. The V<sub>PP</sub> supply voltage is permitted up to 14V for program operation. So the voltage over 14V should not be applied to the V<sub>PP</sub> terminal. When the switching pulse voltage is applied to the V<sub>PP</sub> terminal, the overshoot voltage of its pulse should not be exceeded 14V.

#### **ERASURE CHARACTERISTICS**

The TMM27256AD's erasure is achieved by applying shortwave ultraviolet light which has a wavelength of 2537Å (Angstroms) to the chip through the transparent window.

Then integrated dose (ultraviolet light intensity [w/cm²] x exposure time [sec.]) for erasure should be a minimum of 15 [w·sec/cm²]

When the Toshiba sterilizing lamp GL-15 is used and the device is exposed at a distance of 1cm from the lamp surface, the erasure will be achieved within 60 minutes. And using commercial lamps whose

ultraviolet light intensity is a 12000  $[\mu w/cm^2]$  will reduce the exposure time to about 20 minutes. (In this case, the integrated dose is 12000  $[\mu w/cm^2] \times (20 \times 60)$  [sec]  $\cong 15$  [w·sec/cm<sup>2</sup>].)

The TMM27256AD's erasure begins to occur when exposed to light with wavelength shorter than 4000Å. The sunlight and the flourescent lamps will include 3000~4000Å wavelength components. Therefore when used under such lighting for extended periods of time, the opaque seals-Toshiba EPROM Protect Seal AC901-are available.

### **OPERATION INFORMATION**

The TMM27256AD's six operation modes are listed in the following table. Mode selection can be

achieved by applying TTL level signal to all inputs.

MODE	PIN NAMES(NUMBER)	CE (20)	OE (22)	V <sub>PP</sub> (1)	Vcc (28)	0 <sub>0</sub> ~0 <sub>7</sub> (11~13, 15~19)	POWER
Read Operation (Ta=0~70°C)	Read	L	L			Data Out	Active
	Output Deselect	*	Н	5 V	5V	High Impedance	Active
	Standby	Н	*			High Impedance	Standby
Program Operation (Ta=25±5°C)	Program	L	Н			Data In	Active
	Program Inhibit	Н	Н	12.5V	6V	High Impedance	Active
	Program Verify	*	L			Data Out	Active

Note H: VIH, L: VIL, \*: VIH or VIL

#### **READ MODE**

The TMM27256AD has two control functions. The chip enable  $(\overline{\text{CE}})$  controls the operation power and should be used for device selection.

The output enable  $(\overline{\text{OE}})$  control the output buffers, independent of device selection.

Assuming that  $\overline{CE} = \overline{OE} = V_{IL}$ , the output data is valid at the outputs after address access time from

stabilizing of all addresses.

The  $\overline{\text{CE}}$  to output valid (tce) is equal to the address access time (tacc).

Assuming that  $\overline{CE}=V_{IL}$  and all addresses are valid, the output data is valid at the outputs after too from the falling edge of  $\overline{OE}$ .

### **OUTPUT DESELECT MODE**

Assuming that  $\overline{CE}=V_{IH}$  or  $\overline{OE}=V_{IH}$ , the outputs will be in a high impedance state.

So two or more TMM27256AD's can be con-

nected together on a common bus line.

When  $\overline{CE}$  is decoded for device selection, all deselected devices are in low power standby mode.

### STANDBY MODE

The TMM27256AD has a low power standby mode controlled by the CE signal.

By applying a high level to the CE input, the TMM27256AD is placed in the stancby mode which

reduce 70% of the operating current by applying TTL-high level ( $V_{CC}$ ) and then the outputs are in a high impedance state, independent of the OE inputs.

#### **PROGRAM MODE**

Initially, when received by customers, all bits of the TMN 27256AD are in the "1" state which is erased state.

Therefore the program operation is to introduce "Os" data into the desired bit locations by electrically programming.

#### PROGRAM VERIFY MODE

The verify mode is to check that desired data is correctly programmed on the programmed bits.

#### PROGRAM INHIBIT MODE

Under the condition that the program voltage ( $\pm$  12.5V) is applied to V<sub>PP</sub> terminal, a TTL high level  $\overline{\text{CE}}$  input inhibits the TMM27256AD from being programmed.

Programming of two or more TMM27256AD's in parallel with different data is easily accomplished.

# HIGH SPEED PROGRAMMING MODE

The program time can be greatly decreased by using this high speed programming mode. The device is set up in the high speed programming mode when the programming voltage ( $\pm 12.5V$ ) is applied to the V<sub>PP</sub> terminal with V<sub>CC</sub> = 6V.

The programming is achieved by applying a single TTL low level 1ms pulse to the CE input after addresses and data are stable. Then the programmed data is verified by using Program Verify Mode.

If the programmed data is not correct, another

The TMM27256AD is in the programming mode when the  $V_{PP}$  input is at 12.5V and  $\overline{CE}$  is at TTL-low level under  $\overline{OE}$  =  $V_{IH}$ .

The TMM27256AD can be programmed any location at anytime either individually, sequentially, or at random.

The verify is accomplished with  $\overline{OE}$  at  $V_{IL}$  and  $\overline{CE}$  at  $V_{IH}$  or  $V_{IL}$ .

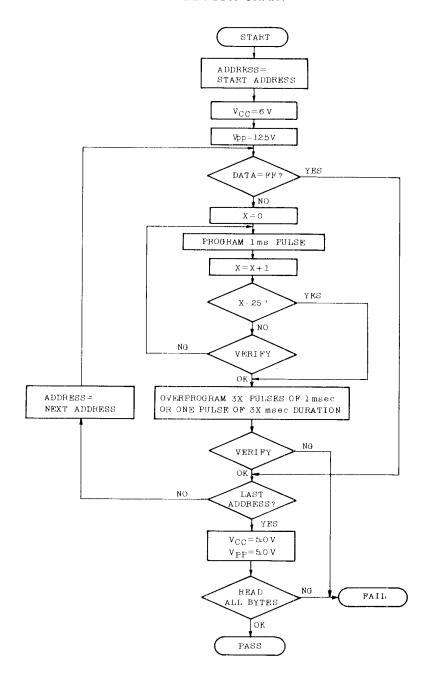
That is , all inputs except for CE and ÖE may be commonly connected, and a TTL low level program pulse is applied to the CE of the desired device only and TTL high level signal is applied to the other devices.

program pulse of 1ms is applied and then the programmed data is verified. This should be repeated until the program operates correctly (max. 25 times).

After correctly programming the selected address, the add tional program pulse with width 3 times that needed for initial programming is applied.

When programming has been completed, the data in all addresses should be verified with  $V_{CC}\!=\!V_{PP}$  = 5V.

## HIGH SPEED PROGRAM MODE FLOW CHART



### **ELECTRIC SIGNATURE MODE**

Electric signature mode allows to read out a code from TMM27256AD which identifies its manufacturer and device type.

The programming equipment may read out manufacturer code and device code from TMM27256AD by using this mode before program operation and automatically set program voltage (Vpp) and algorithm.

Electric signature mode is set up when 12V is

applined to address line A<sub>9</sub> and the rest of address lines is set to  $V_{IL}$  in read operation. Data output in this conditions is manufacturer code. Device code is identified when address A<sub>0</sub> is set to  $V_{IH}$ . These two codes possess an odd parity with the parity bit of MSB  $(O_7)$ .

The following table shows electric signature of  $\mathsf{TMM27256AD}$ .

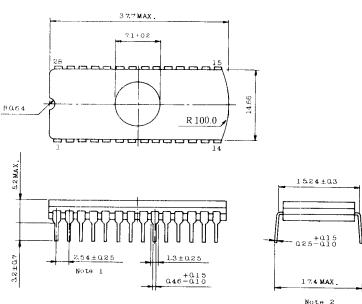
PINS SIGNATURE	Ao (10)	C <sub>7</sub> (19)	O <sub>6</sub> (18)	O <sub>5</sub> (17)	O <sub>4</sub> (16)	O <sub>3</sub> (15)	O <sub>2</sub> (13)	O <sub>1</sub> (12)	O <sub>0</sub> (11)	HEX. DATA
Manufacture Code	Vil	. 1	0	0	1	1	0	0	0	98
Device Code	Viii	0	1	0	1	0	1	0	0	54

Notes:  $A_9 = 12V \pm 0.5V$ 

A1-A8, A10-A14, CE, OE = VII

## **OUTLINE DRAWINGS**

Unit in mm



- Note: 1. Each lead pitch is 2.54mm. All leads are located within 0.25mm of their true longitudinal position with respect No. 1 and No.28 leads.
  - 2. This value is measured at the end of leads.
  - 3. All dimensions are in millimeters.

Note: Toshiba does not assume any responsibility for use of any circuitry described; no circuit patent licenses are implied, and Toshiba reserves the right, at any time without notice, to change said circuitry.

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